Switching Diodes

Panasonic

MA271110G

Silicon epitaxial planar type

For high-speed switching circuits

Features

- High-density mounting is possible
- \bullet Short reverse recovery time $t_{\rm rr}$
- Small terminal capacitance C_t

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	80	V
Maximum peak reverse voltage	V _{RM}	80	V
Forward current	$I_{\rm F}$	100	mA
Peak forward current	I_{FM}	225	mA
Non-repetitive peak forward surge current *	I _{FSM}	500	mA
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

- Package
- Code SSSMini2-F3
 Pin Name
- 1: Anode
 - 2: Cathode

Marking Symbol: S

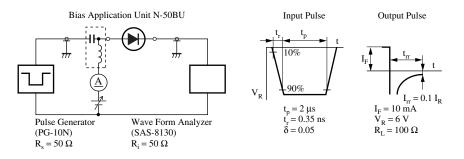
Note) *: t = 1 s

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

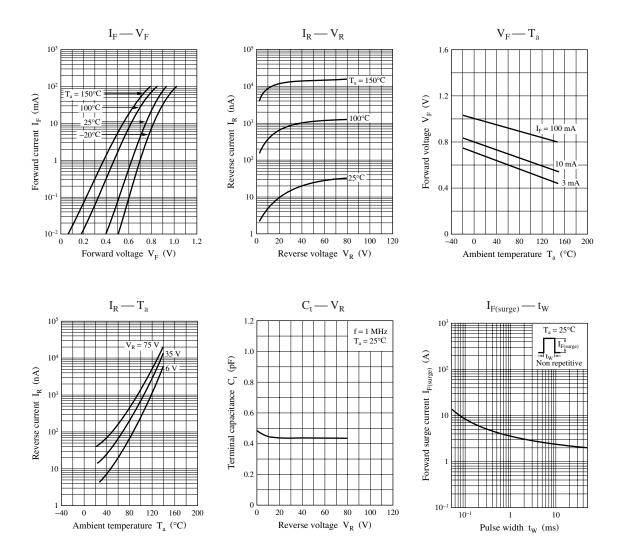
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 100 \text{ mA}$		0.95	1.20	V
Reverse voltage	V _R	$I_R = 100 \ \mu A$	80			
Reverse current	I _R	V _R = 75 V			100	nA
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		0.6	2.0	pF
Reverse recovery time *	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			3	ns
		I_{rr} = 0.1 I_R , R_L = 100 Ω				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. Absolute frequency of input and output is 10 MHz.
 - 3. *: t_{rr} measurement circuit



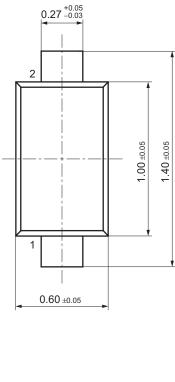
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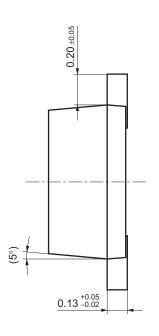


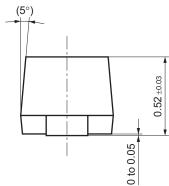
Panasonic

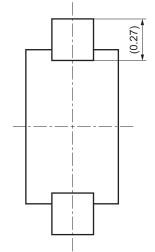
SSSMini2-F3

Unit: mm









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